

			1 3"	
L	Hits	Search Text	DB	Time stamp
Number			,	
1	1016389	copper or Cu	USPAT;	2003/10/31
			US-PGPUB;	18:59
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	423795	adhesion	USPAT;	2003/10/31
			US-PGPUB;	18:59
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	178820	seed	USPAT;	2003/10/31
	1,0020	Secu	US-PGPUB;	19:00
			EPO; JPO;	13.00
			DERWENT;	
			IBM TDB	
4	4863	(copper or Cu) and adhesion and seed	USPAT;	2003/10/31
	4003	(copper of cu) and adhesion and seed	US-PGPUB;	19:00
				19:00
			EPO; JPO;	
			DERWENT;	
5			IBM_TDB	
	2164702	w or tungsten	USPAT;	2003/10/31
			US-PGPUB;	19:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	3235	' ' ' ' E' ' ' ' ' ' ' ' '	USPAT;	2003/10/31
		and (w or tungsten)	US-PGPUB;	19:01
			EPO; JPO;	
			DERWENT;	
			IBM TDB	·
7	235210	interconnect	USPAT;	2003/10/31
			US-PGPUB;	19:01
			EPO; JPO;	
			DERWENT;	İ
			IBM TDB	
8	1190	(((copper or Cu) and adhesion and seed)	USPAT;	2003/10/31
		and (w or tungsten)) and interconnect	US-PGPUB;	19:02
		distribution of the state of th	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	1	1	I TOU IDD	i .